



**Manufacturing Roadmap for Heterogeneous Integration and Electronics Packaging
(MRHIEP)**

Agenda for in- person publication of draft roadmap

Room # 154 Moscone Center South, San Francisco CA

2.00 pm PST to 4.30 pm PST, July 10th, 2023

Time	Topic	Speaker
2.00 – 2.20 pm	Introduction and Goals	Subramanian Iyer
2.20 – 3.00 pm	Process and tooling	Venky Sundaram, Eric Forsythe
3.00 – 3.20 pm	Cross cutting issues: modeling, thermal and reliability	Benson Chan
3.20 – 3.35 pm	Mechanical and electrical standards	Bapi Vinnakota
3.35 – 4.00 pm	Supply chain, security, test and smart manufacturing	Mark da Silva
4.00 – 4.30 pm	Panel discussion on next steps, Refreshments	Moderated by Gity Samadi
4.30 pm	Adjourn	